

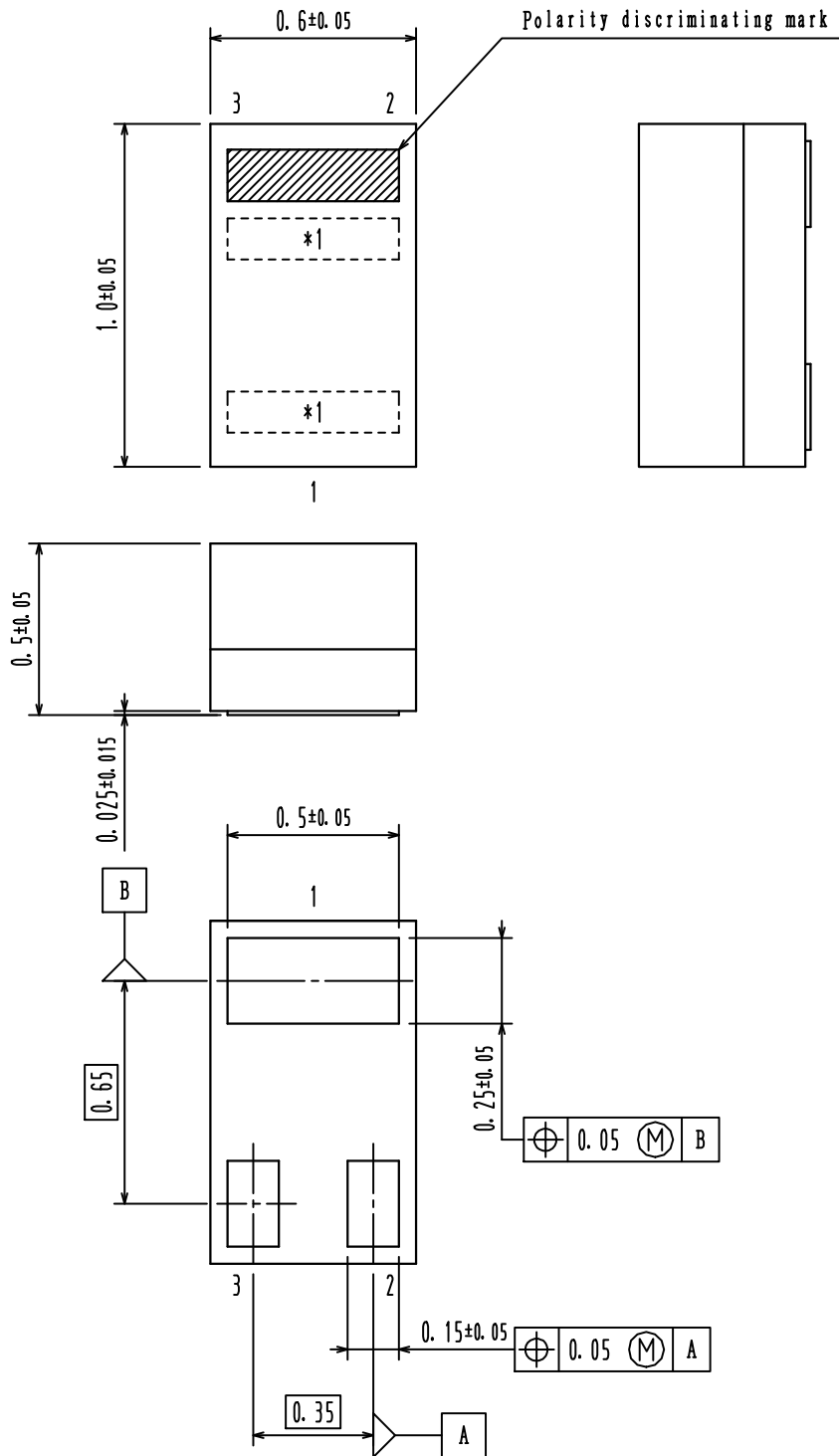
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

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**ECSP1006-3**  
**CASE 971AT**  
**ISSUE 0**

DATE 30 JAN 2012



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